

Amendments to the Specification

At page 1, line 2, after the title of invention and before the first paragraph please insert the following subtitle:

Technical Field

At page 1, line 7, before the second paragraph please insert the following subtitle:

Background Art

At page 4, line 29 between the penultimate paragraph and last paragraph please insert the following subtitle:

Brief Summary of the Invention

At page 5, line 1 before the first paragraph please insert the following new paragraph followed by the new subtitle:

The above object is accomplished through processes for wet-chemical treatment of one side of a silicon wafer using a liquid bath, during which the wafer lays on conveyor means and the entire surface of the underside to be treated is conveyed through or over liquid located in the liquid bath. In a first embodiment, the conveyor means are positioned within the liquid bath and the top side, which is not to be treated, is always positioned above the liquid. In a second embodiment, the level of the liquid being contacted by the underside is maintained above the level of the bath surface not being contacted by the underside. The top side, which is not to be treated, is always positioned above the level of the liquid.

Detailed Description of the Invention